



**THE DATASHEET OF  
NUF9002FCT1G**



# NUF9002FC

## Low Capacitance 10 Line EMI Filter with ESD Protection

This device is a ten-line EMI filter array for wireless applications. Greater than -25 dB attenuation is obtained at frequencies from 900 MHz to 3.0 GHz. ESD protection is provided across all capacitors.

### Features

- EMI Filtering and ESD Protection
- Integration of 50 Discretes
- Provides Protection for IEC61000-4-2 (Level 4)
  - ◆ 8.0 kV (Contact)
- Flip-Chip Package
- Moisture Sensitivity Level 1
- ESD Rating: Machine Model = C; Human Body Model = 3B
- Pb-Free Package is Available\*

### Benefits

- Reduces EMI/RFI Emissions on a Data Line
- Integrated Solution Offers Cost and Space Savings
- Reduces Parasitic Inductances Which Offer a More “Ideal” Low Pass Filter Response
- Integrated Solution Improves System Reliability

### Applications

- LCD for Cell Phones and PDAs
- Computers and Printers
- Communication Systems
- MP3 Players

### MAXIMUM RATINGS (T<sub>A</sub> = 25°C unless otherwise noted)

Rating		Symbol	Value	Unit
ESD Discharge IEC61000-4-2	Contact Discharge	V <sub>PP</sub>	8.0	kV
Steady-State Power per Resistor		P <sub>R</sub>	100	mW
Steady-State Power per Package		P <sub>T</sub>	200	mW
Operating Temperature Range		T <sub>OP</sub>	-40 to +85	°C
Storage Temperature Range		T <sub>STG</sub>	-55 to +150	°C
Junction Temperature		T <sub>J</sub>	+125	°C

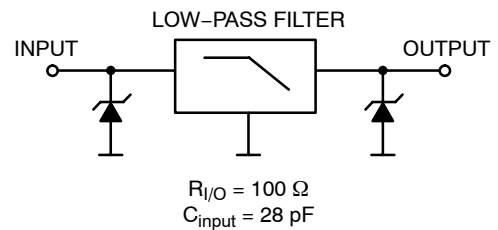
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

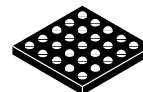


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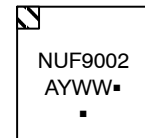
<http://onsemi.com>



### MARKING DIAGRAM



A1 Flip-Chip  
CASE 499G

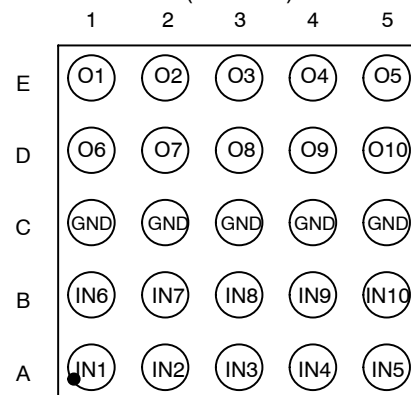


NUF9002 = Specific Device Code  
A = Assembly Location  
Y = Year  
WW = Work Week  
▪ = Pb-Free Package

(Note: Microdot may be in either location)

### PIN CONFIGURATION

(Ball Side)



### ORDERING INFORMATION

Device	Package	Shipping†
NUF9002FCT1	Flip-Chip	3000 Tape & Reel
NUF9002FCT1G	Flip-Chip (Pb-Free)	3000 Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

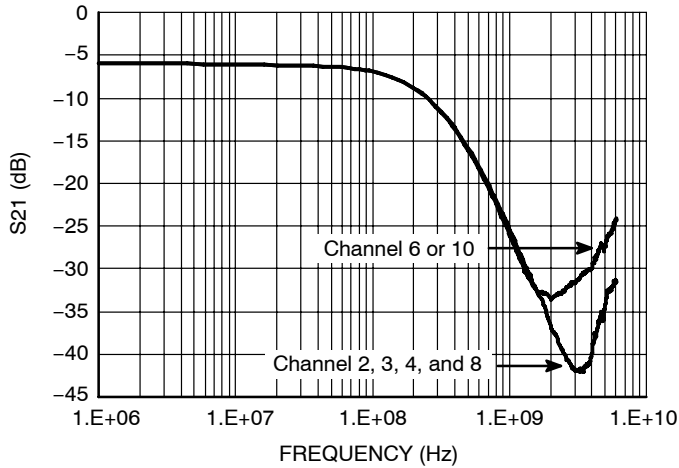
# NUF9002FC

## ELECTRICAL CHARACTERISTICS (T<sub>A</sub> = 25°C unless otherwise noted)

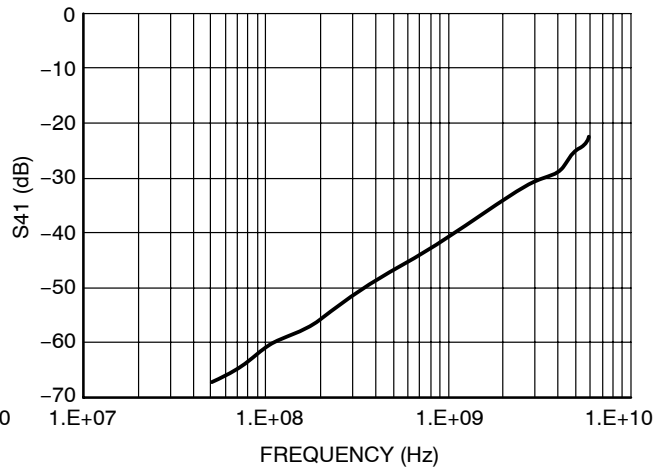
Characteristic	Symbol	Test Conditions	Min	Typ	Max	Unit
Maximum Reverse Working Voltage	V <sub>RWM</sub>	–	–	–	5.0	V
Breakdown Voltage	V <sub>BR</sub>	I <sub>R</sub> = 1.0 mA	6.0	7.0	8.0	V
Leakage Current	I <sub>R</sub>	V <sub>RM</sub> = 3.0 V	–	–	0.1	μA
Series Resistance	R <sub>A</sub>	–	85	100	115	Ω
Capacitance	C <sub>LINE 1</sub>	f = 1.0 MHz, 0 Vdc	–	28	35	pF
Cut-Off Frequency	f <sub>3dB</sub>	(Above this frequency, appreciable attenuation occurs)	–	110	–	MHz

## TYPICAL PERFORMANCE CURVE

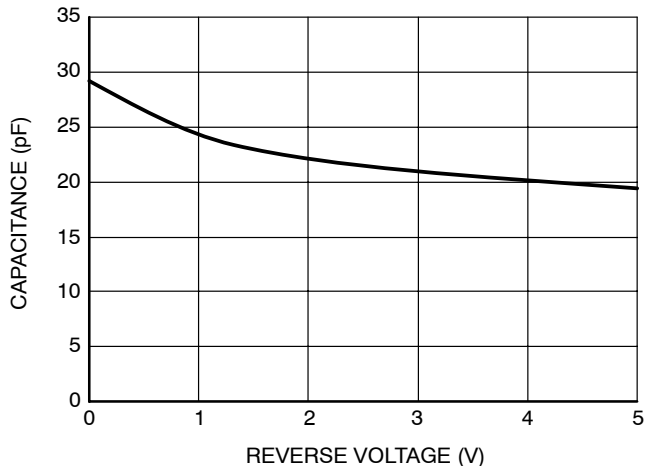
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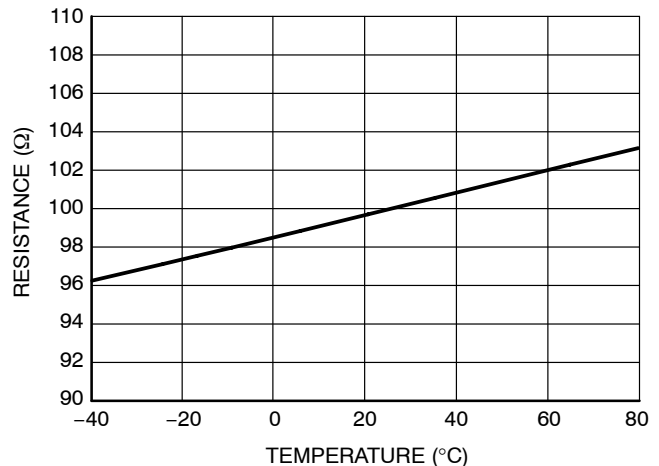
**Figure 1. Insertion Loss Characteristics (S21 Measurement)**



**Figure 2. Analog Crosstalk Curve (S41 Measurement)**



**Figure 3. Typical Line Capacitance vs. Reverse Bias Voltage**



**Figure 4. Typical Resistance Over Temperature**

PRINTED CIRCUIT BOARD RECOMMENDATIONS

Parameter	500 $\mu\text{m}$ Pitch 300 or 350 $\mu\text{m}$ Solder Ball
PCB Pad Size	250 $\mu\text{m}$ +25 -0
Pad Shape	Round
Pad Type	NSMD
Solder Mask Opening	350 $\mu\text{m}$ $\pm$ 25
Solder Stencil Thickness	125 $\mu\text{m}$
Stencil Aperture	250 x 250 $\mu\text{m}$ sq.
Solder Flux Ratio	50/50
Solder Paste Type	No Clean Type 3 or Finer
Trace Finish	OSP Cu
Trace Width	150 $\mu\text{m}$ Max

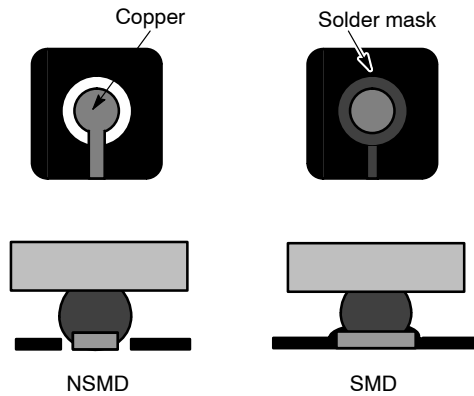
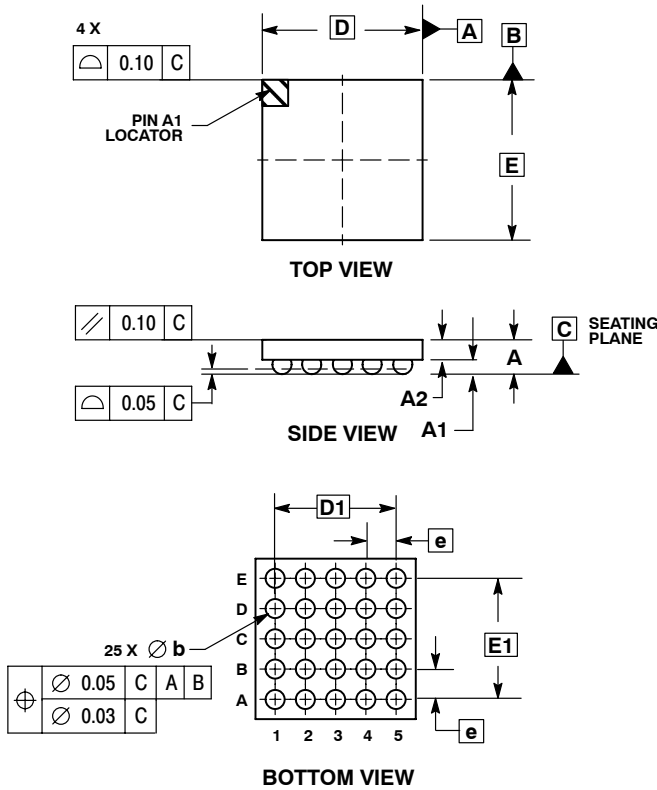


Figure 5. NSMD vs. SMD

# NUF9002FC

## PACKAGE DIMENSIONS

FLIP-CHIP-25 CSP  
CASE 499G-01  
ISSUE A



**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

DIM	MILLIMETERS	
	MIN	MAX
A	---	0.650
A1	0.210	0.270
A2	0.380	0.430
D	2.650 BSC	
E	2.650 BSC	
b	0.290	0.340
e	0.500 BSC	
D1	2.000 BSC	
E1	2.000 BSC	

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